New in RevC : OSC X6, R100/R900/R901 pull-up, CN3 3x2

Text to be added to silkscreen.
Warning text.

Notes to generate the board layout.

Open Platform License Agreement

The Open Platform License Agreement ("Agreement") is a binding legal contract between you ("You") and STMicroelectronics International N.V. ("ST"), a company incorporated under the laws of the Netherlands acting for the purpose of this Agreement through its Swiss branch 39, Chemin du Champ des Filles, 1228 Plan-les-Ouates, Geneva, Switzerland.

By using the enclosed reference designs, schematics, PC board layouts, and documentation, in hardcopy or CAD tool file format (collectively, the "Reference Material"), You are agreeing to be bound by the terms and conditions of this Agreement. Do not use the Reference Material until You have read and agreed to this Agreement terms and conditions. The use of the Reference Material automatically implies the acceptance of the Agreement terms and conditions.

The complete Open Platform License Agreement can be found on www.st.com/opla.

Open Platform License Agreement